PRODUCT SPECIFIICATION

GS12864C-D-BSXTSWW-100

V1.0

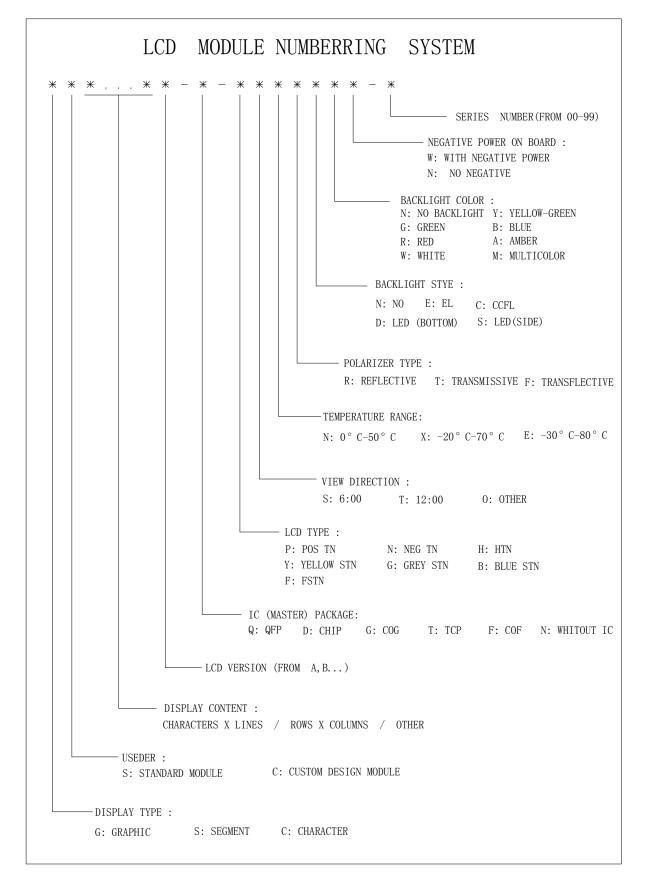
February 20, 2009



REVISION RECORD

VERSION	DESCRIPTION	DATE
V1.0	First Release	Feb 20, 2009

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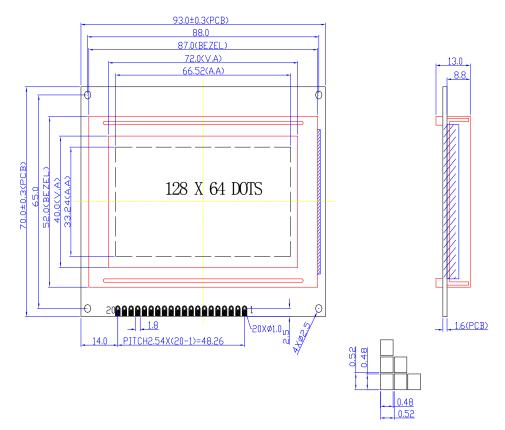
2. TYPE NUMBER AND DESCRIPTION

Type Number	:	GS12864C-D-BSXTSWW-100
Description	:	128 X 64 DOTS
LCD Panel	:	Blue-STN ,Negitive, Transmissive
Viewing angle	:	6H
Duty	:	1/64
Bias	•	1/9
Backlight	:	White ,Side
Logic Voltage	:	5.0V
Operating Temperatu	re:	-20°C70°C
Storage Temperature	:	-30°C80°C
Controller	:	KS0107B&KS0108B or Equivalent
Package	:	Bonding

ITEM	STANDARD VALUE	UNIT			
DISPLAY CONTENT	128H X 64V DOTS				
MODULE DIMENSION	93.0(W) X 70.0(H) X 13.0(T)	mm			
EFFECTTVE DISPLAY AREA	72.0(W) X 40.0(H)	mm			
DOT SIZE	0.48(W) X 0.48(H)	mm			
DOT PITCH	0.52(W) X 0.52(H)	mm			
APPROX WEIGHT	TBD	g			
LCD TYPE	STN (Blue mode)				
DUTY AND BIAS	1/64 DUTY; 1/9 BIAS				
VIEWING DIRECTION	6:00				
BACK LIGHT	White LED				

3. MECHANICAL SPECIFICATIONS:

MODLE DIMENSION DRAWING



V 1.0 -----

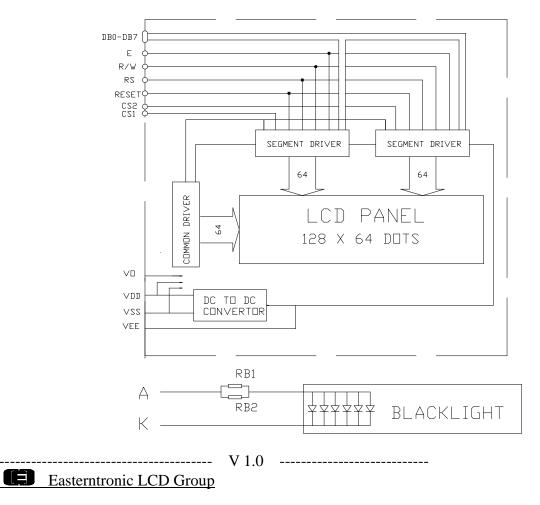
* Remark : General tolerance refers this model. (±0.2mm)

4. ELECTRICAL BLOCK DIAGRAM

4.1 PIN DEFINITION

PIN	SYMBOL	FUNCTION					
1	VSS	Power Supply (GND)					
2	VDD	Power Supply (+5V)					
3	VO	Contrast Adjust					
4	RS	Data or Instruction(H: Display Ram Data)					
5	R/W	Read or Write (H: Data Appears at Data Bus)					
6	Е	Enable Signal					
7-14	DB0-DB7	Data Bus					
15	/CS1	Select Chip1, H Active					
16	/CS2	Select Chip2, H Active					
17	/RST	Reset Signal, L Active					
18	VEE	Negative Voltage					
19	А	Power Supply For Backlight (+)					
20	K	Power Supply For Backlight (-)					

4.2 ELECTRICAL BLOCK DIAGRAM



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5. ABSOLUTE MAXIMUM RATINGS

ELECTRICAL MAXIMUM RATINGS 5.1

5.1 Electrical Maximum Ratings (Ta=25deg C)

	0	. 0 ,			
ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Supply Voltage (Logic)	Vdd – Vss	25 C	0	7.0	V
Supply Voltage (LCD Drive)	Vdd – Vee	25 C	-	18.0	V
Input Voltage	Vi	-	-0.3	Vdd +0.3	V

5.2 Environmental Conditions

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	Dry	-20	70	deg C
Storage Temp	Ttsg	Dry	-30	80	deg C

6. ELECTRICAL SPECIFICATIONS

6.1 Electrical Characteristics at Ta=25 deg C, Vdd = 5V + / - 5%

		<u> </u>				
ITEM	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
Supply Voltage (logic)	Vdd-Vss	-	4.5	5.0	5.5	V
Supply Voltage (LCD)	Vdd-V0	Vdd = 5V		8.8	9.2	V
Input signal voltage	Vih	"H" level	2.4	-	Vdd	V
(for E, DB0-7,R/W,RS)	Vil	"L" level	0	-	0.6	V
Output voltage for Logic	Voh	-Ioh=0.6mA	Vdd- 0.4	-	Vdd	V
LOGIC	Vol	Iol=1.6mA	0	-	0.4	
Supply Current	Idd	-		8.0	10.0	mA
Supply Voltage (LED)	VLED		2.9	3.1	3.3	V
Supply Current (LED)	lf		-	80	120	mA

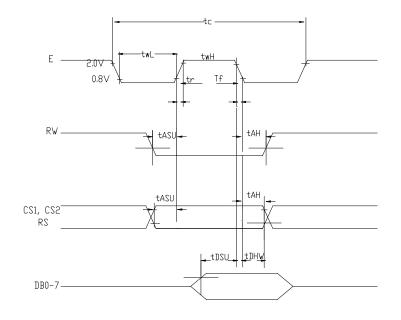
6.2 TIMING SPECIFICATIONS at Ta = 25 deg C, Vdd = 5V+/-10%, Vss =0V

ITEM	SYMBOL	MIN	MAX	UNIT
E Cycle Time	tc	1000	-	ns
E High Level Width	tWH	450		ns
E Low Level Width	tWL	450		ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
Address Set-Up Time	tASU	140	-	ns
Address Hold Time	tAH	10	-	ns
Data Set-up Time	tDSU	200	-	ns
Data Delay Time	tD	-	320	ns

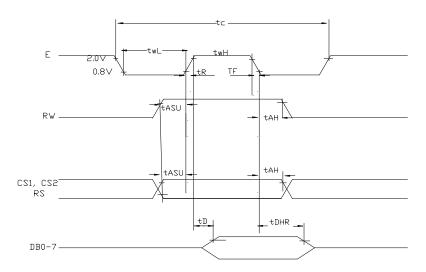
----- V 1.0 -----Easterntronic LCD Group

Data Hold Time(Write)	tDHW	10	ns
Data Hold Time(Read)	tDHR	20	ns

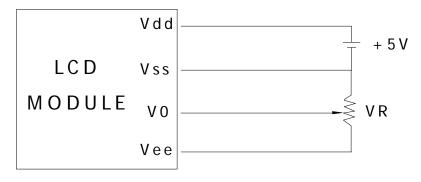
MPU WRITE TIMING



MPU READ TIMING



7. POWER SUPPLY FOR LCD MODULE



Vdd-V0: LCD Driving Voltage VR: 10K - 20K

8. ELECTRO-OPTICAL CHARACTERISTIC

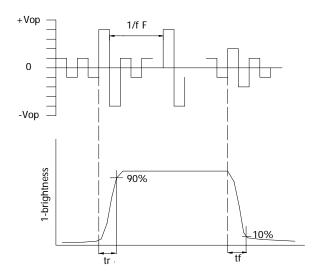
ITEM	SYMBOL	CONDITI ON	MIN.	TYP.	MAX.	UNIT	REF.
Contrast	CR	25 ℃		12			Note1
Rise Time	tr	25 ℃		160	240	ms	Note2
Fall Time	tf	25 ℃		100	150	ms	note 2
	θ 1- θ 2	25 ℃			60	DEG	Noto 2
Viewing Angle	Ø1, Ø2	250	-40		40	DEG	Note 3
Frame Frequency	Ff	25 ℃		70		Hz	note 2

Note(1): Contrast ratio is defined under the following condition:

- CR= <u>brightness of selected condition</u> brightness of non- selected condition
- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle----- $\theta = 0, \ \emptyset = 0$
- (d). Operating Voltage---8.8V

Note(2): definition of response time:

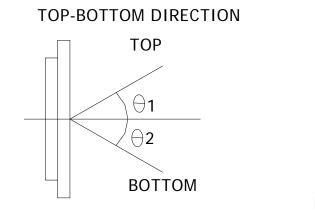
----- V 1.0 -----



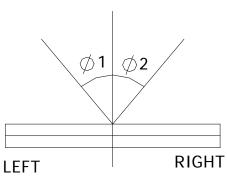
Condition:

- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
- (c). Viewing angle------ $\theta = 0$, Ø=0
- (d). Operating Voltage---8.8V

Note(3): definition of view angle:



RIGHT-LEFT DIRECTION



V 1.0 -----

9. INSTRUCTION TABLE

Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function
Display ON/OFF	L	L	L	L	Н	I	H	H	Т	L/H	Controls the display on or off. Internal status and display RAM data is not affected. L:OFF, H:ON
Set Address (Yaddress)	L	L	L	Η		Υa	ddress	(0~63)			Sets the Y address in the Y address counter.
Set Page (Xaddress)	L	L	Η	L	Н	Н	Н		Page (0~7)		Sets the X address at the X address register.
Display Start Line (Z address)	L	L	Η	Η		I		start line 63)	9		Indicates the display data RAM displayed at the top of the screen.
Status Read	L	H	B U S Y	L	ON/OFF	R E S E T	L	L	L	L	Read status. BUSY L: Ready H: In operation ON/OFF L: Display ON H: Display OFF RESET L: Normal H: Reset
Write Display Data	Η	L				Write D)ata				Writes data (DB0:7) into display data RAM. After writing instruction, Y address is increased by 1 automatically.
Read Display Data	Η	Η				Read D)ata				Reads data (DB0:7) from display data RAM to the data bus.

1. Display On/Off

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	1	1	1	D

The display data appears when D is 1 and disappears when D is 0.

Though the data is not on the screen with D=0, it remains in the display data RAM. Therefore, you can make it appear by changing D=0 into D=1.

2. Set Address (Y Address)

S R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 0 0 0 1 AC5 AC4 AC3 AC2 AC1 AC0	_			71000100	~,~,						
0 0 0 1 AC5 AC4 AC3 AC2 AC1 AC0	_	S	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
	С	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

Y address (AC0 ~ AC5) of the display data RAM is set in the Y address counter. An address is set by instruction and increased by 1 automatically by read or write operations of display data.

3. Set Page (X Address)

RS	ĨŔŴ	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	1	1	AC2	AC1	AC0

X address(AC0 ~ AC2) of the display data RAM is set in the X address register. Writing or reading to or from MPU is executed in this specified page until the next page is set.

4. Display Start Line (Z Address)

RS	Í R/W	DB ₇	DB6 (DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	AC5	AC4	AC3	AC2	AC1	AC0

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Z address (AC0 ~ AC5) of the display data RAM is set in the display start line register and displayed at the top of the screen.

When the display duty cycle is 1/64 or others(1/32 ~ 1/64), the data of total line number of LCD screen, from the line specified by display start line instruction, is displayed.

5. Status Read

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	BUSY	0	ON/OFF	RESET	0	0	0	0

- BUSY When BUSY is 1, the Chip is executing internal operation and no instructions are accepted. When BUSY is 0, the Chip is ready to accept any instructions.
- ON/OFF When ON/OFF is 1, the display is on. When ON/OFF is 0, the display is off.
- RESET

When RESET is 1, the system is being initialized.

In this condition, no instructions except status read can be accepted.

When RESET is 0, initializing has finished and the system is in the usual operation condition.

6. Write Display Data

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	D7	D6	D5	D4	D3	D2	D1	DO

Writes data (D0 ~ D7) into the display data RAM.

After writing instruction, Y address is increased by 1 automatically.

7. Read Display Data

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	1	D7	D6	D5	D4	D3	D2	D1	DO

Reads data (D0 ~ D7) from the display data RAM.

After reading instruction, Y address is increased by 1 automatically.

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10.Quality units

10.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

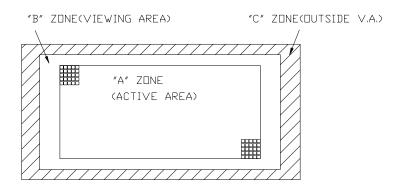
10.2 Scope

This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

10.3 Definition

10.3.1 Definition of area

- A Zone: Active area.
- B Zone: Viewing area
- C Zone: Outside viewing area.



10.3.2 Definition of size

Large size(L): 1~6 pcs LCD screens are cut out of from each 14"×16" mother glass. Middle size(M): 7~50 pcs LCD screens are cut out of from each 14"×16" mother glass. Small size(S): more than 50 pcs LCD screens are cut out of from each 14"×16" mother glass.

10.4 Quality Specification

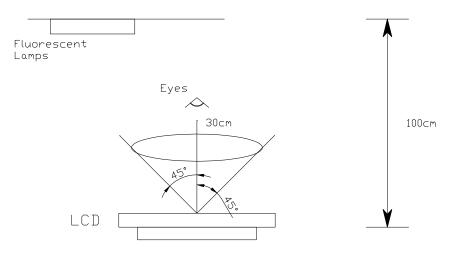
10.4.1 Conditions of Cosmetic Inspection

10.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 \pm 5°C. Ambient humidity: 65 \pm 20%RH Ambient Luminance: 40-watt fluorescent lamp.

------ V 1.0 -----

An appearance test should be conducted by human sight at approximately 30 cm distance from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is 45° from vertical against LCD.



10.4.1.2 When test the model of transmissive product must add the reflective plate.

10.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

10.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.

- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0

V 1.0

10.4.4 Applicable instrument

- LCD module tester
- Multimeter
- Caliper
- Defect size filming standard

10.4.5 Inspection quality criterion

10.4.5.1 LCD panel part

The inspection specification	as following list:
------------------------------	--------------------

Classify	Item	Description of	Inspectio	on criterion	Drawing
		defects			specification
Major defect	1.Non-display	Product no function	Not	accept	
	2.LCD with wrong view direction`	Difference in Spec.	Not	accept	
	3.Segment missing	Part or all pattern do not light up	Not	accept	
	4.Occur high current	Current exceed designed value	Not	accept	
	5. LC leakage	LC does not fulfill the glass cell	Not	accept	
	6.Deviation	LCM Dimension	According	to dimensions	
	from drawing	difference from drawing and over tolerance	noted in the	e specification	
	7.Wrong type applied	Wrong polarizer attachment	Not	accept	
		Pin attached wrong type applied	Not	accept	
	8.Incorrect pins quality	Pin attached wrong quantity applied	Not	accept	
Minor defect	9.Pattern deformation	Segment fatter or smaller	Dimension (mm) A≤0.1	Acceptable number Not count (Should not be connected to	

----- V 1.0 -----

				next dot)	
				next dot)	
			0.10 <a≤0.15< td=""><td>1 pc / dot(only</td><td></td></a≤0.15<>	1 pc / dot(only	
				segment)or less	
				2 pcs / cell or	
				less	
				(Should not be	
				connected to	
				next dot)	
				,	
			B ≤ 0.10	Not count	
Minor	10.Pinholes	Black spot/white	1. large size	e LCD	
defect		spot at activated	-	n't be found at	
		state	1m distanc	e and will not	
			enlarge unde	er electronic test	
			2. Middle si	ize LCD	
			Diameter(mr	n) Accept QTY	
			$\Phi \leq$ 0.15	Not count	X
			$0.15 < \Phi \le 0.25$	3	
			$0.25 < \Phi \le 0.35$	5 1	$\Phi = (X+Y)/2$
			$\Phi > 0.35$	5 0	
			3. Small siz	e LCD	
			Diameter(mr	n) Accept QTY	
			$\Phi \leq 0.15$	Not count	
			$0.15 < \Phi \le 0.25$	2	
			$0.25 < \Phi \le 0.30$	1	
			$\Phi > 0.30$) 0	
			4. For the	1	
				f the area of	
				s less than or	
			-	half of one	
			lattice's		
			-	ow one defect in	
			one segm		
				liatance allowed	
				wo pinholes is	
	11 D1 1			0mm	
	11.Blemishes	Black spot/dust	Positive pan	ei:	
	and foreign	0n I CD(non diaplay	1.A zone		↓ ↓ ↓
	matters	LCD(non-display	- Large size I		
)		an't find at 1m	X
			uistance and	will not enlarge	

	r
under electronic test:	$\Phi = (X+Y)/2$
-Middle size LCD	
Diameter(mm) Accept QTY	
$\Phi \le 0.15$ Not count	
$0.15 < \Phi \le 0.25$ 3	
0.25<Φ≤0.35 1	
$\Phi \! > \! 0.35$ 0	
-Small size LCD	
Diameter(mm) Accept QTY	
$\Phi \le 0.15$ Not count	
0.15<Φ≤0.25 2	
0.25<Φ≤0.30 1	
$\Phi \! > \! 0.30$ 0	
2.B zone	
1.5 times of acceptable	
largest diameter size of Zone	
Α	
3.C zone	
Notcount.	
Negative panel:	
1. A zone	
-Large size LCD	
Diameter(mm) Accept QTY	
$\Phi \le$ 0.15 Not count	
$0.15 < \Phi \le 0.30$ 4	
$0.30 < \Phi \le 0.50$ 1	
$\Phi \! > \! 0.50$ 0	
-Middle&small size LCD	
Diameter(mm) Accept QTY	
$\Phi \le 0.15$ Not count	
$0.15 < \Phi \le 0.25$ 3	
$\Phi \! > \! 0.25$ 0	
2. B zone	
1.5 times of acceptable	
largest diameter size of Zone	
A	
3.C zone	
No count	
The nearest diatance allowed	
between two black spot is	
20mm	

12.Black	Scratch on glass	Positive panel:	
lines and	or polarizer	1.A zone	
scratches	surface.And	- Large size LCD	
serucenes	foreign linear	Accept if can't find at 1m	
	matters in LCD	distance and will not enlarge	
		under electronic test.	
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		W≤0.02 Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 3$ 2	
		$0.02 < W \le 0.03, L > 4$ 0	
		$0.03 < W \le 0.05, L \ge 3$ 0	
		W>0.05 As the spot criteria.	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		$W \le 0.02$ Not count	
		$0.02 < W \le 0.03, L \le 4$ 2	
		$0.03 < W \le 0.05, L \le 2$ 1	
		$0.02 < W \le 0.03, L > 4 $ 0	
		$0.03 < W \le 0.05, L \ge 2$ 0	
		W>0.05 As the spot criteria.	
		2.B zone	
		1.5 times of acceptable largest	
		diameter size of Zone A	
		3.C zone	
		Notcount.	
		Negative panel:	
		1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY	
		W≤0.02 Not count	
		$0.02 < W \le 0.03, L \le 5$ 3	
		$0.03 < W \le 0.05, L \le 4$ 2	
		$0.02 < W \le 0.03, L > 5$ 0	
		$0.03{<}W{\leq}0.05{,}L$ $>{4}$ 0	
		W>0.05 As the spot criteria.	

			-Middle size LCD Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 4$ 2 $0.03 < W \le 0.05, L \le 2$ 2 $0.02 < W \le 0.03, L > 3$ 0 $0.03 < W \le 0.05, L > 2$ 0 W > 0.05 As the spot criteria. -Small size LCD Diameter(mm) Accept QTY $W \le 0.02$ Not count $0.02 < W \le 0.03, L \le 3$ 2 $0.03 < W \le 0.05, L \le 3$ 1 $0.02 < W \le 0.05, L \ge 2$ 0 W > 0.05 As the spot criteria. 2. B zone 1.5 times of acceptable largest diameter size of Zone A 3.C zone Not count The nearest diatance allowed between two defects is 20mm	
Mintor defect	13. Scratch on PI coating	PI coating scratched	The visible scratch of A zone can not be accepted at 30cm view distance.	
Mintor defect	14. Rainbow	Arches,circular or parallel colorful spread	According to the limit specimen	
Mintor defect	15. Bubbles or wrinkles in polarizer	Bubbles or wrinkles between polarizer and glass	A zone:The visible defect can not be accepted at 30cm view distance. B zone: Not count	
Mintor defect	16. Position of polarzer attachment	Wrong polarizer attachment in position or dimension	Polarizer protruding from edge of glass and exceeding/within the maximum external dimension of LCD	

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· · · · ·		1					Γ
Mintor	17. Ink	17.1 Ink	Not accept				
defect	printing	line/pattern					
	defect	broken					
		17.2 Ink	-	f the thick		-	
		pattern/line	less than	n equal to	25% s	segment	
		jagged	width, o	r accordii	ng to tl	he limit	
			specimer	n			
		17.3 Light	When	activated	with	current	
		leakage	white lig	ht appears	s in the	position	
			of pinho	ole or scra	atch due	e to ink	
			printing	misalignr	nent.Ac	cording	
			to the pir	nhole spec	ificatio	n.	
		17.4 Ink printing	Reject if	the thick	or thin	in more	
		pattern/line	than 1/2	W.			
		uneven	Reject w	hen W1-V	V2≤1/3V	W	
							↑ ₩1 ↑ ₩2
Mintor	18. Pin defect	18.1 Corrosion	Pin	incomin	g	defect:	``
defect		or foreign	oxidized	,damage(i	ncludin	g pins	
		material on	plating	damaged)	,excess	epoxy	
		terminal legs	on bott				
			legs.Not accept.				
		18.2 Pin	According to the specification				
		deviation over					
		tolerance		-			
Mintor	19. Chipped	19.1 Chip in	a	b	c	accept	
defect	glass on	lead contact				QTY	
	comer	area.	a≤5mm	b≤W	c≤T		
			L>5m			3	ITO
			m				
			a <l< td=""><td>b≤W</td><td>c≤T</td><td>3</td><td></td></l<>	b≤W	c≤T	3	
			T				
			L<5m				b f f
			m				
		19.2 Others	Not exc	ceed $1/2$			
			width of	seal	c≤T	3	
I		V 1.0				1	- 21 -

Mintar	20 Class	ahin on adaa	0	h		0.000mt	
Mintor defect	20. Glass chip on edge		a	b	с	accept QTY	
			a≤5mm	Not exceed 1/2 width of seal	c≤T	3	C C
Mintor	21. Clipped electrode pad	21.1Glass chip on ITO edge	a	b	с	accept QTY	ITD
defect	I		a≤4mm (and not exceed 4 ITO termina 1	b≤W/4	c≤T	3	
		21.2 Glass chip on ITO back	a	b	с	accept QTY	Q A A
			a≤5mm	b≤W/3	c≤T	3	T T
Mintor defect	22. Mechanical			b		QTY	
	damage	attempt to remove the chip with tweezers,re-eval uate if the remaining defect is still a crack or a chip	b≤W/4		2		
Mintor defect	23.Gla	Not acce	pt	1			
defect Q Large siz Middle s	imum space be TY in total: ze LCD: Zone A size LCD: Zone	tween any 2 defec ≤ 5/unit, Zone B≤ 5 A≤ 3/unit, Zone B≤ ≤ 2/unit, Zone B≤ 2	/unit; 3/unit;	rt) should	l more	than 20m	m, and max. allowed

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10.4.5.2 Other part

NO.	Items	Criterion of defects	AQL
1	Backlight	 Lumination source flickers. Using spot, lines and contamination standard of LCD to 	Major Minor
		judge the spots or scratches defect on backlight.	Major
		•	
		4. Colour and luminance of backlight should correspond its	Major
2	PCB,COB	specification. 1.COB seal may not have pinholes larger than0.2mm or	Minor
2	TCD,COD	contamination.	WIIIOI
		2.COB seal surface may not have pinholes through to the IC.	Minor
		3. The height of COB should not exceed the height indicated	Major
		in the assembly diagram.	
		4. Beyond 2mm of the seal area, there may not have sealant on the PCB.	Minor
		5.No oxidation or contamination on PCB connector.	Minor
		6.Parts on PCB should correspond the characteristic, and not	Major
		allow wrong parts, missing parts or additional parts.	
		7.The jumper on the PCB should correspond to the characteristic.	Minor
		8. The solder which gets on bezel, LED pad, zebra pad or	Major
		screw hole pad should be smoothed down.	Major
		1. No unmelted solder pastes on the PCB.	Minor
3	Soldering	2. No cold solder joints, solder connection missing, oxidation	Minor
		of solder.	
		3. No short circuits in components on PCB.	Minor
4	General Appearance	1. No oxidation, contamination, curves, cracks or bends on interface Pin of TCP.	Minor
		2. No solder residue or solder balls on product.	Minor
		3. The IC on TCP may not be damaged.	Major
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Minor
		5. Packing method correspond the specification.	Major
		6. Dimension and structure correspond the specification sheet.	Major
		7. No dirt and break on the heat seal.	Major
		1	1

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The inspection specification as following list:

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10.5 Reliability

Item	Condition	Criterion			
High temperature operation	$+70^{\circ}\text{C}\pm2^{\circ}\text{C}$, 8 ho				
Low temperature	-20°C \pm 2°C , 8 ho	1.Total current			
operation		I	consumption		
Humidity	Operation	$40^{\circ}C \pm 2^{\circ}C$,93% ± 2 % RH,8	should be below		
		hours	double of initial		
	Storage	$40 \degree C \pm 2 \degree C$,93% $\pm 2\%$ RH,	value.		
		24 hours	2.Cosmetic defects		
High temperature	$+80^{\circ}C \pm 2^{\circ}C$, 10 h	nours	should not be		
storage			happened		
Low temperature	$-30^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 10 h	ours			
storage					
Thermal shock	-20°C∼+70°C				
storage	60min~60min, 5 cy				
Vibration test	-	mm,frequency:50Hz,30min			
	in each direction(X				
Shock test	To be measured aft				
	80cm high on the c				
	state.(weight≥15k				
	Weight <15Kg, dro				
	E F				
	G B				
	60/8				
Remark: The function test shall be conducted after 4 hours storage at the normal					
temperature and hu	umidity after remove	d from the test chamber.			

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The LCD module shall not fail the following reliability test.

11. PRECAUTION FOR USING LCM

1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The following precautions should be taken when handing.

(1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.

(2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.

(3). Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.

(4). Glass can be easily chipped or cracked from rough handing. especially at corners and edges. (5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

(1). Do not tamper in any way with the tabs on the tabs on the metal frame.

Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.

(3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).

(4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.

(5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing piels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

(2). The modules should be kept in antistatic

bags or other containers resistant to static for storage.

(3). Only properly grounded soldering irons should be used.

(4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks. (5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.

(6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.

2.3. Soldering

(1). Solder only to the I/O terminals.

(2). Use only soldering irons with proper grounding and no leakage.

(3). Soldering temperature: 280 $^\circ\!\mathrm{C}\pm10^\circ\!\mathrm{C}$

Soldering time: 3 to 4 sec. (4).

(5). Use eutectic solder with resin flux fill.

If flux is used, the LCD surface should be (6). covered to avoid flux spatters. Flux residue should be removed after wards.

2.4. Operation(1). The viewing angle can be adjusted by varying the LCD driving voltage V0.

(2). Driving voltage should be kept within specified range; excess voltage shortens display life.

(3). Response time increases with decrease in temperature.

Display may turn black or dark blue at (4). temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".

(5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6. Limited Warranty

Unless otherwise agreed between ORIENT DISPLAY and customer, ORIENT DISPLAY will replace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with ORIENT DISPLAY acceptance standards, for a period on one year fron data of shipment. Confirmation of such date shall be based on freight The warranty liability of ORIENT documents. DISPLAY is limited to repair and/or replacement on the terms set forth above. ORIENT DISPLAY will not responsible for any subsequent or consequential events.

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Declaration of conformity regarding the limitation of dangerous substances

深圳易事通液晶显示模块有限公司

SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

BaoAn District, ShenZhen, P.R. China

DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS SUBSTANCES

WE , SHENZHEN EASTERNTRONIC LCM CO ., LTD,

Declare that the product of GS12864C-D-BSXTSWW-100 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation

of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

• Lead

• Mercury

●Cadmium

•Hexavalant chromium

●Polybrominated biphenyls

●Polybrominated diphenylethers

And to the annex which points out the exempted implementations

□ To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

• Oils containing polychlorinated bipheny1

• Asbestos

• Radioactive substances

Name: Ding

SHENZHEN EASTERNTRONIC LCM CO., LTD.

Issued on Feb 20,2009

According with the proposal of Technical Adaption Committee(TAC) of a limit of 0.1% by weight for lead hexavalent

chromium, mercury, PBBs and PBDRs and 0.01% by weight for Cadmium

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